

REMARKS

In the present amendment, claim 1 and 6 has been amended, claims 2-5 and 7-13 have been cancelled, and new claims 14 and 15 have been added. Accordingly, claims 1, 6, 14, and 15 are pending in the application, with claim 1 being the independent claim.

Applicants note that claim 1 has been amended by adding the embodiments that the active layer wafer and the supporting wafer are covered on the top and back surfaces with films made of the same material, and that the thicknesses of said films are differentiated in order to induce a warp for bonding. Support for the amendment can be found, e.g., at page 8, paragraphs [0016] and [0017]; and page 17, paragraph [0035].

New dependent claims 14 and 15 are specifically directed to the structure of the supporting wafer. Support for these claims can be found in the originally filed specification, at, e.g., page 17, paragraph [0035] to page 18, paragraph [0036].

Response to Objections to the Specification

The Office Action asserts that the title is not descriptive and requires a new title.

In response, Applicants have amended the title. Accordingly, withdrawal of the objection is requested.

The Office Action further objects to the specification pointing out a grammatical error on page 4, lines 28-30, with respect to the term "either."

Applicants note that the specification has been amended in response. In addition, the same type of language has been corrected at page 6, paragraph [0011] and at page 7, paragraph [0013].

Response to Claim Objections

The Office Action objects to claims 2-4 because of the same type of informality as described above with respect to the specification to the specification.

In response, Applicants respectfully note that in view of the cancellation of claims 2-4, the objections to the claims is moot and should be withdrawn.

Response to Rejection under 35 U.S.C. § 102(e)

The Office Action rejects claims 1, 6, and 7 under 35 U.S.C. § 102(e) as allegedly being anticipated by U.S. Patent No. 6,756,285 to Moriceau et al., hereinafter "MORICEAU."

In response, Applicants respectfully note that in order to advance prosecution of the application, and without expressing agreement with or acquiescence to the rejection, claim 1 has been amended by adding the embodiments that "at least either one of said active layer wafer or said supporting wafer are covered with film layers of the same material on the top and the back surfaces thereof, and wherein the film materials of said active layer wafer and said supporting wafer are different from the film materials of said active layer wafer and said supporting wafer;" and that "the film thickness on the top surface side is differentiated from the film thickness on the back surface side of said active layer wafer and said supporting wafer, thereby generating a warp in said active layer wafer and said supporting wafer and bonding said fitting surfaces together." Support for the amendment can be found, e.g., at page 8, paragraphs [0016] and [0017]; and page 17, paragraph [0035]. Moreover, claims 2-5 and 7-13 have been cancelled and new dependent claims 14 and 15 have been added.

Applicants note that MORICEAU does not disclose an active layer wafer and a supporting layer wafer with a warp, wherein the film thickness of the top surface film is

differentiated from the film thickness of the back surface film, and wherein the top surface film and the bottom surface film are being made of the same material. MORICEAU discloses that a wafer is provided with a warp when being bonded and that the silicon wafer is curved by adhering an oxide film or a nitride film to the silicon wafer. MORICEAU does not disclose to differentiate the film thicknesses in order to induce a warp. Moreover, MORICEAU does not disclose that the top surface film and the bottom surface film are covered with film layers of the same material.

Accordingly, Applicants respectfully request withdrawal of the anticipation rejection of record.

Response to rejections under 35 U.S.C. § 103(a)

The Office Action makes the following rejections under 35 U.S.C. § 103(a):

- claims 2-5 and 8-13, as allegedly being unpatentable over MORICEAU in view of U.S. 2001/0029072 to Kuwahara et al. and U.S. Patent No. 5,071,785 to Nakazato et al.;
- claims 4, 9, and 12, as allegedly being unpatentable over MORICEAU in view of U.S. Patent No. 5,362,667 to Linn et al. and Nakazato et al.

In response, as pointed out above, in order to advance prosecution of the application and without expressing agreement with or acquiescence to the rejection, claims 1 and 6 have been amended, claims 2-5 and 7-13 have been cancelled and new claim 14 and 15 have been added.

Applicants respectfully request withdrawal of the obviousness rejections.

CONCLUSION

In view of the foregoing, it is believed that all of the claims in this application are in condition of allowance, which action is respectfully requested. If any issues yet remain which can be resolved by a telephone conference, the Examiner is respectfully requested to contact the undersigned at the telephone number listed below.

Respectfully submitted,
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